

Datasheet revision 1.2

CHIPQUIK®

Germanium Doped Solder Wire Sn/Cu0.7/Ni0.05/Ge0.006 no-clean .031 1lb

Product Highlights

This eutectic alloy has a uniform grain structure and produces bright shiny joints with no shrinkage. The germanium in our CQ100Ge[™] alloy acts as an anti-oxidant which significantly reduces dross when used in solder pots and wave soldering machines. **No-Clean** Synthetic Flux Core The clear, non-corrosive, non-conductive residue is meant to be left on the board. 2.2% flux core Halogen content: None **RoHS 3 and REACH compliant**

| Specifications | |
|----------------------|-------------------------------|
| Alloy: | Sn99.244/Cu0.7/Ni0.05/Ge0.006 |
| Wire Diameter: | 0.031" (0.8mm) |
| Flux Type: | No-Clean Synthetic |
| Flux Classification: | ROL0 |
| Melting Point: | 227°C (441°F) |
| Packaging: | 1 lb spool |
| Shelf Life: | >60 months |

Test Results

| Test Requirement | Result |
|---|---|
| IPC-TM-650: 2.3.32 | L: No breakthrough |
| IPC-TM-650: 2.6.15 | L: No corrosion |
| IPC-TM-650: 2.3.28.1 | L: <0.05% |
| IPC-TM-650: 2.6.14.1 | L: <1 decade drop (No-clean) |
| IPC-TM-650: 2.6.3.7 | L: ≥100MΩ (No-clean) |
| IPC-TM-650: 3.4.2.5 | Clear and free from precipitation |
| Electronic Industry Citizenship Coalition (EICC) | Compliant |
| Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |
| | IPC-TM-650: 2.3.32 IPC-TM-650: 2.6.15 IPC-TM-650: 2.3.28.1 IPC-TM-650: 2.6.14.1 IPC-TM-650: 2.6.3.7 IPC-TM-650: 3.4.2.5 Electronic Industry Citizenship Coalition (EICC) Articles 33 and 67 of Regulation (EC) |

| Conforms to the following Industry Standards: | |
|---|-----|
| J-STD-004B, Amendment 1 (Solder Fluxes): | Yes |
| J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): | |
| RoHS 3 Directive (EU) 2015/863: | Yes |